

ABSTRACT OF THE DISCLOSURE

A fast curing composition that comprises a polymeric resin, a conductive filler and one or more near-infrared absorbing additives and optionally an oxygen scavenger or corrosion inhibitor or both, and other additives such as reactive or nonreactive diluents, inert fillers, and adhesion
5 promoters. The composition may be conductive, resistive or anisotropically conductive. In another embodiment, this invention is a method for improving the cure speed of a composition by exposing the composition to a near infrared energy source.

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